


MATERIAL DECLARATION SHEET



Material Number	CD0201-T20C			
Product Line	Semiconductor Products			
Compliance Date				
RoHS Compliant	Yes	MSL	1	

No.	Construction Element(subpart)	Homogeneous Material	Material weight [mg]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Wafer	Silicon	0.03000	Silicon	7440-21-3	100.00%	11.237%	11.237%
2	Lead frame	Copper Alloy	0.00026	Tin	7440-31-5	0.25%	0.097%	39.242%
			0.00021	Zinc	7440-66-6	0.20%	0.079%	
			0.00028	Chromium	7440-47-3	0.27%	0.105%	
			0.10282	Copper	7440-50-8	98.13%	38.512%	
			0.00110	Nickel	7440-02-0	1.05%	0.412%	
			0.00008	Palladium	7440-05-3	0.08%	0.030%	
			0.00002	Gold	7440-57-5	0.02%	0.007%	
3	Epoxy	Polymer	0.00720	Silver	7440-22-4	72.00%	2.697%	3.746%
			0.00080	Modified Epoxy Resin	Proprietary	8.00%	0.300%	
			0.00070	2-(2-ethoxyethoxy)ethyl acetate	112-15-2	7.00%	0.262%	
			0.00040	CP formaldehyde&aniline,maleated	Proprietary	4.00%	0.150%	
			0.00020	Carbonic Ester	Proprietary	2.00%	0.075%	
			0.00040	Acrylic resin	Proprietary	4.00%	0.150%	
			0.00030	Epoxy resin	Proprietary	3.00%	0.112%	
4	Wire	Noble metal	0.00900	Aurum	7440-57-5	99.99%	3.371%	3.746%
			0.00100	Others	/	0.01%	0.375%	

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5	Mold Compound	Polymer	0.09537	Fused Silica	60676-86-0	85.00%	35.720%	42.029%
			0.00842	Solid Epoxy Resin	proprietary	7.50%	3.154%	
			0.00281	Phenol resin	proprietary	2.50%	1.053%	
			0.00528	Metal hydroxide	proprietary	4.70%	1.978%	
			0.00033	Carbon black	1333-86-4	0.30%	0.124%	
		Total weight	0.26698 mg					

This Document was updated on: 2016/8/15

Important remarks:

1. It is the responsibility of the user to verify they are accessing the latest version.